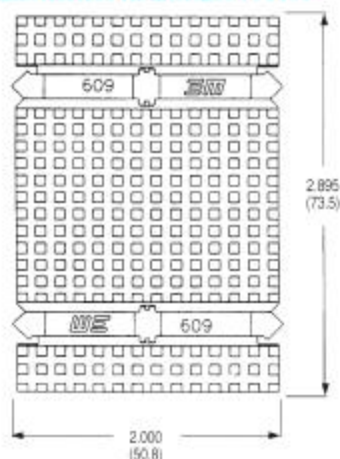




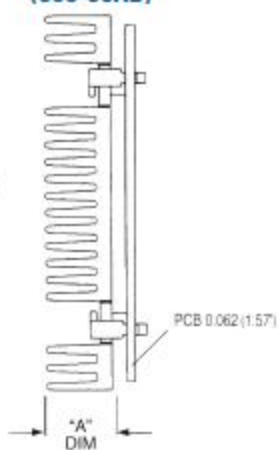
WAKEFIELD SOLUTIONS Data Sheet

Standard P/N	Base Dimensions in. (mm)	Dimensions "A" in. (mm)	Typical Applications	Heat Sink Finish	Weight lbs. (grams)
609-50AB	2.895 (73.5) x 2.000 (50.8)	0.500 (12.7)	40&45mm BGA	Black Anodized	0.094 (42.5)
609-100AB	2.808 (71.32) x 1.700 (43.2)	1.000 (25.4)	40&45mm BGA	Black Anodized	0.130 (59.0)

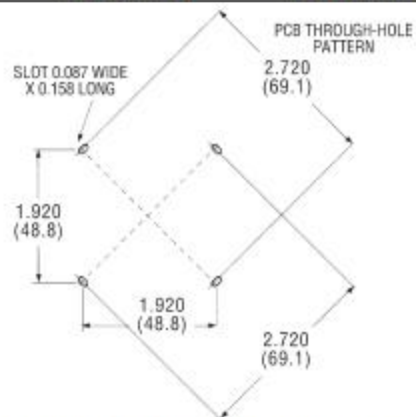
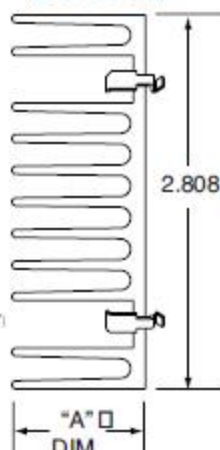
MECHANICAL DIMENSIONS



(609-50AB)



(609-100AB)



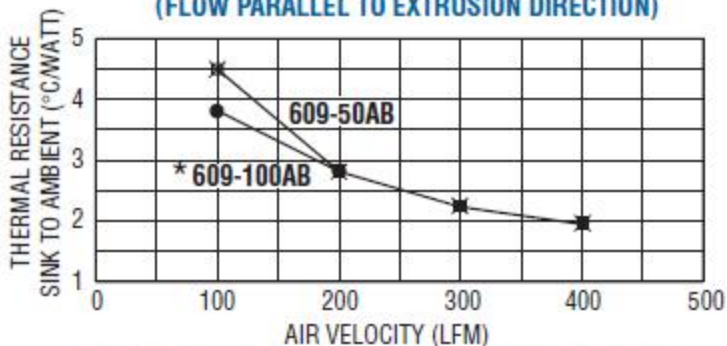
Designed to fit a .063" thick PCB electronic package thickness of .110"

Dimensions: in. (mm)



609-50AB HEAT SINK AND CLIP ASSEMBLY

FORCED CONVECTION THERMAL PERFORMANCE DATA (FLOW PARALLEL TO EXTRUSION DIRECTION)



*Performance is for shrouded conditions. 609-100 will perform better than 609-50 in cases with bypass.

Mouser Electronics

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[Wakefield-Vette:](#)

[609-100ABS3](#)